

Free Space Isolator Epoxy (FSIE Series)

Rev 11B

Description

The Free Space Isolator Epoxy is designed for integration within laser diode package to prevent back reflection. The high isolation, low insertion loss and large aperture features make the optical isolator epoxy flexible to fit with different diode laser packaging requirements.

Key Features

- High Isolation
- Low Insertion Loss

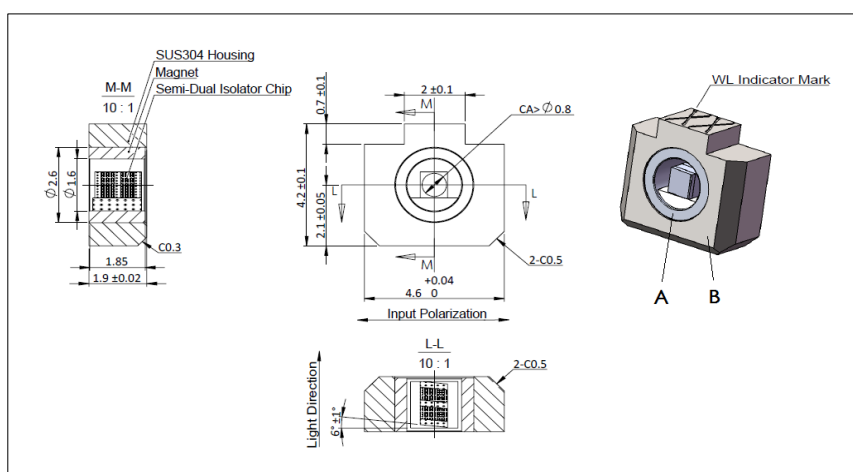
Applications

- Laser Chip

Specifications

Parameter	Unit	Value
Stage	-	Single Stage Dual Stage
Center Wavelength (λ_c)	nm	1310 or 1550
Typ. Insertion Loss	dB	0.12 0.20
Max. Insertion Loss	dB	0.30 0.50
Peak Isolation	dB	40 55
Min. Isolation, 23 °C	dB	30 40
Clear Aperture	mm	0.4 - 0.9
Max. Optical Power (Continuous Wave)	mW	300
Polarization Plane of Input	-	Indicated in package diagram
Tilt Angle of Input Plane	degree	6
Operating Temperature	°C	0 to + 60
Storage Temperature	°C	- 40 to + 85

Package Dimensions



Ordering Information

FSIE-①-②②-③③-④

①: Stage

1 - Single Stage

2 - Semi-Double Stage

②②: Wavelength

31 - 1310 nm

48 - 1480 nm

55 - 1550 nm

SS - Specify

③③: Clear Aperture

07 - Ø 0.7 mm

08 - Ø 0.8 mm

09 - Ø 0.9 mm

SS - Specify

④: Package

1 - Ø 2.6 × Ø 1.6 × 1.85 mm Magnet, No Housing (Refer to A)

2 - Ø 2.2 × Ø 1.6 × 1.7 mm Magnet, No Housing

3 - 4.6 × 1.9 × 4.2 - Ø 2.6 mm Housing (Refer to B)

4 - 3.5 × 1.7 × 3.85 - Ø 2.2 mm Housing

S - Specified